Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]
HP ProBook 4545s Notebook PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Yes, MB</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Yes,Battery pack ,RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries No</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Yes</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Yes, AC power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. No</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>No</td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers | No | 0
---|---|---
Components, parts and materials containing radioactive substances | No | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>T8 Torx</td>
<td>T8</td>
</tr>
<tr>
<td>Cross</td>
<td>#1</td>
</tr>
<tr>
<td>Slot</td>
<td>2.5*50</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Took off the battery module and Service door
2. Took off Thermal Fan and Thermal Heat Sink
3. Took off HDD and ODD unit
4. Took off U-case and Keyboard Unit
5. Took out Main Board
6. Took off LCD Unit
7. Took off LCD Module
8.  

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Pebble 15” Tear Down report

2012/03/30
N20E10
Jonathan Hsu
Process – 1 Remove Battery and Service Door

Get Component Sequence:
Slide both latches inward to release Battery pack and Service Door
Process – 2 Remove Thermal Unit

Get Component Sequence:
Release marked screws to release RCTO bracket.
Process – 2 Remove Thermal Unit Cont’

Get Component Sequence:
1. Release marked screws
2. Remove Thermal Fan unit.
3. Remove Thermal Heat Sink.
Process – 3 Remove HDD and ODD unit

Get Component Sequence:
1. Release marked screws to remove ODD Module and HDD unit.
Process – 4 Remove U-Case

Get Component Sequence:
1. Release ALL marked screws (18 Screws)
Process – 4 Remove U-Case Cont’

Get Component Sequence:
1. Slide Keyboard Backward
2. Remove keyboard by flipping it over
Get Component Sequence:
1. Release marked Screw
2. Unplug all cable connectors and FFC before disassemble U-case
Get Component Sequence:
1. Release marked Screw to take out MB at once.
Process – 6 Remove LCD Unit

Get Component Sequence:
Release marked Screws.
Process – 6 Remove LCD Unit Cont’

Get Component Sequence:
1. Release marked Screws.
2. Remove both sides Hinge cap

Hint: When removing hinge caps
Pinch it and give it a little twist
Get Component Sequence:
Remove LCD Bezel by pulling 4 sides inside out.
Process – 7 Remove LCD Module

Get Component Sequence:
Release marked Screws (6) to remove LCD module
Thank You!